Tracewell T-FX2e

**BASED ON:** The Dell EMC PowerEdge FX architecture. Converged platform houses flexible blocks of server, storage and I/O resources while providing efficiency through shared power, networking and management.

**USE CASE:** Ideal for customers that need to add significant storage density to Dell Technologies’ modular, converged FX architecture in order to support their high-performance and specialty computing needs.

**Benefits**

**DELL TECHNOLOGIES**

Enterprise-class modular infrastructure that combines the density and efficiency of blades with the simplicity and cost benefits of rack systems. Flexible and customizable servers, storage and networking.

**TRACEWELL PLATFORMS**

The Dell EMC FX architecture in a short-depth form factor. Each Tracewell T-FX2e supports four Extended Storage Modules per system, or one for each standard Dell EMC compute sled. With the capacity to add 8 drives per ESM, the T-FX2e makes it possible to add a total of 32 2.5” additional storage drives per platform.

**DELL TECHNOLOGIES + TRACEWELL**

Electrically identical to standard Dell EMC products. “Plug and play” components between Dell EMC products and Tracewell platforms. Order through Dell EMC (Dell EMC part number) and eligible for Dell EMC warranty, service, support and secure supply chain.

**FORM FACTOR HIGHLIGHTS:**

Short-depth form factor delivers an enterprise class, converged platform with enhanced storage density.

Features the Tracewell Extended Storage Module (ESM), which enhances system capabilities by adding up to (8) 2.5” drives to each T-FX2he platform.

**PRODUCT AT A GLANCE**

6.9”H x 19.0”W x 23.7”D (17.5”W not including ears)
The Tracewell T-FX2e Specifications Summary

The Tracewell T-FX2e accepts standard Dell hardware configurations.

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### STANDARD DELL EMC PRODUCT CONFIGURATIONS

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<tr>
<th><strong>PROCESSOR TYPE</strong></th>
<th>Half Width (HW): Intel® 2nd generation Xeon® Scalable processors, up to 28 cores per processor (1 or 2 processors).</th>
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<tbody>
<tr>
<td><strong>MEMORY ARCHITECTURE</strong></td>
<td>HW: 16 DDR4 DIMM slots, supports RDIMM/LRDIMM, up to 2933MT/s speeds, 2TB Max DDR4.</td>
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<tr>
<td><strong>RAID CONTROLLER</strong></td>
<td>Hardware RAID, Levels 0, 1, 5, 10 or pass through.</td>
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| **STORAGE** | Processing Sleds: (HW), up to ten 2.5" drives with Extended Storage Module (ESM), SAS/SATA, SSD/HDD. Standard FC640" with onboard SATA to PCH, 1 or 2 drives.  
Optional ESM with PERC RAID controller, up to 8 drives. Internal SD vFlash site.  
Optional internal USB and dual SD sites (hypervisor).  
* Each FC640 can be equipped with one ESM or a Drive Expansion Module (DEM filler panel.) |
| **VIDEO** | G200 (integrated with iDRAC). FC640 4GB; video memory shared with iDRAC application memory. |
| **SLED SLOTS** | Sled bay supports up to four (HW) processing sleds with 4 Extended Storage Modules (ESM). Accepts standard FC640 processing sled with appropriate configuration or filler panels. |
| **I/O MODULES** | Ethernet: Supports up to 2 I/O aggregator modules. Modules are available in pass-through and switching configurations. |
| **CHASSIS MANAGEMENT CONTROLLER** | Single, dual-port chassis management module. Two dedicated 10/100/1000Mb RJ45 ports, one for external management, one for daisy chaining or NIC failover. Serial 9-pin, DTE, 16550 compatible. |
| **FRONT ACCESSIBLE I/O** | One USB 2.0 connector for keyboard and mouse support.  
One additional USB 2.0 connector.  
| **POWER SUPPLY** | Up to two power supplies supported. Available in 2400W / 2000W / 1600W output (per PS). N+1 compatible.  
High-line operation up to 2400W with N+1 redundancy or 3000W* non-redundant.  
Low-line operation up to 1400W with N+1 redundancy or 2800W non-redundant.  
Input voltage: 90-264 VAC.  
* CMC system limits power usage within the system architecture. |
| **COOLING** | Rear removable fan module with high-pressure fans.  
Normal operating temp: 10°C to 35°C (50°F to 95°F). Expanded operating temp: -5°C to 45°C (23°F to 113°F) with some restrictions. Storage temp: -40°C to 65°C (-40°F to 149°F). EMC: Enterprise class FCC emissions. |
## Tracewell Systems Product Configurations

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<th>CHASSIS</th>
<th>Bonded aluminum low-mass chassis for rigidity with minimum weight.</th>
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| RACK INSTALLATION & OPTIONS | 19” rack mount per EIA specification. Front and rear mounting points to allow hard mounting into racks; rear pin option allows blind mating intro racks. Additional mounting locations for sled lock bars. Front handles.  
Optional: Rack mount slides, removable front guard with particle filter and line cord retainer kit. |

For more information, see the Tracewell T-FX2e Data Sheet.

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## About Tracewell Systems

For more than 40 years Tracewell has enabled the nation's largest military and commercial organizations to deliver powerful and reliable computing solutions in environments where size, weight, power and other constraints present challenges that cannot be met by standard computing systems. Tracewell Systems have been recognized by the top names in the defense and technology sectors for their commitment to Trusted Innovation – a process where the company solves previously impossible, sensitive, mission-critical platform challenges through customer solution design, engineering and manufacturing, all under one roof.

More information: [www.tracewell.com](http://www.tracewell.com)